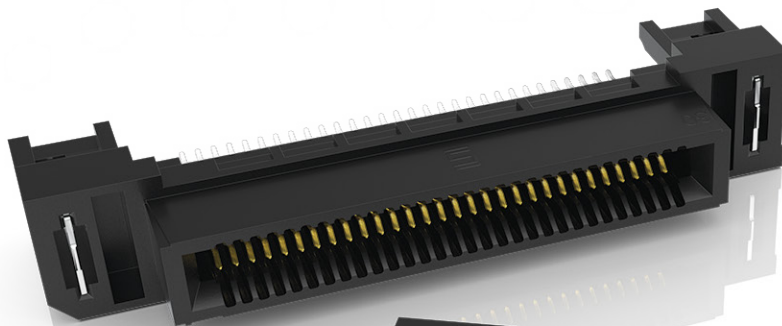


GENERATE[®]

HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH

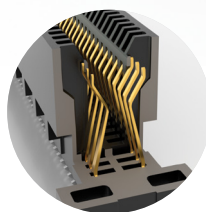
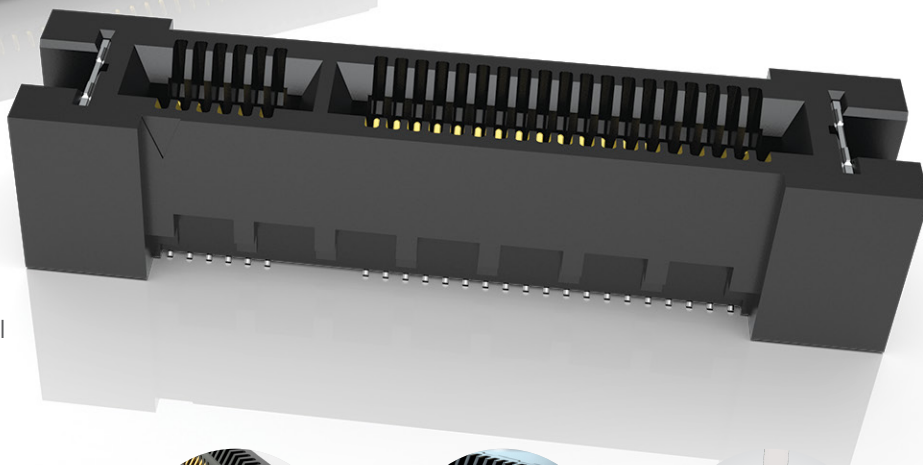


**EDGE
RATE[®]**
CONTACT

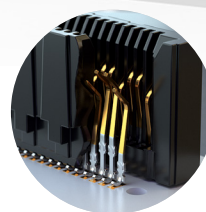
FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express[®] 3.0, 4.0, 5.0 and 6.0
- Edge Rate[®] contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

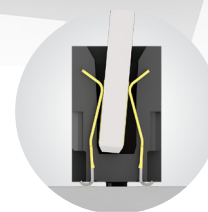
The PCI Express[®] design marks are registered trademarks and/or service marks of PCI-SIG.



Rugged tucked beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



Custom designs allow for misalignment in the X-Y axes (HSEC1)

KEY SPECIFICATIONS

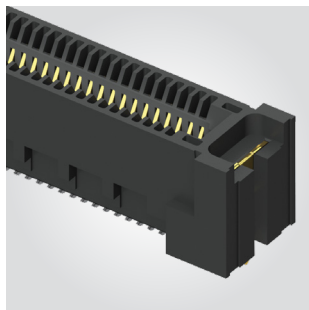
SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC/339 VDC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DV	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-RA	0.80 mm	18-120	Black LCP	BeCu	-55 °C to +125 °C	2.6 A (2 pins)	175 VAC/247 VDC	Yes
HSEC8-EM	0.80 mm	20-120	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PE	0.80 mm	20-40	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PV	0.80 mm	40-80	Black LCP	BeCu	-55 °C to +125 °C	3.2 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DP	0.80 mm	16-112	Black LCP	BeCu	-55 °C to +125 °C	2.7 A (2 pins)	235 VAC/332 VDC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC/304 VDC	Yes

(0.80 mm) .0315" PITCH • RUGGED HIGH-SPEED EDGE CARD SOCKET

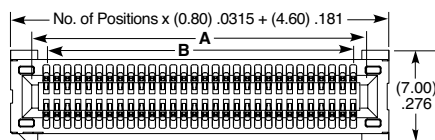
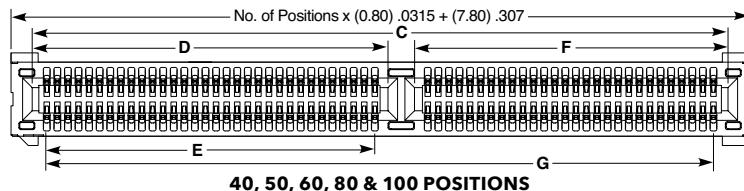
HTEC8	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	DV	OPTION	OTHER OPTION	"X"R
		10, 20, 30, 40, 50, 60, 80, 100	-01 = (1.60 mm) .062" thick card -03 = (2.36 mm) .093" thick card	-L = 10 μm (0.25 μm) Gold on contact area, Matte Tin on tail		Leave blank for no alignment pin -A = Alignment Pin -WT = Weld Tab (-A option required) -BL = Board Lock (-A option required) (Weld tab standard)	-K = (7.00 mm) .276" DIA Polyimide Pick & Place Pad	Leave blank for Tray Packaging -TR = Tape & Reel (10 thru 60 positions only) -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks) (10 thru 60 positions only)

HTEC8

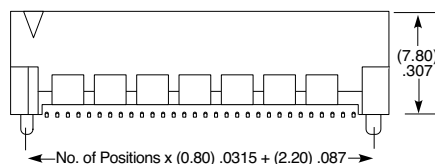
Card Mates:
(1.60 mm) .062"
thick card,
(2.36 mm) .093"
thick card,
HSC8



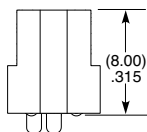
POSITIONS PER ROW	C	D	E	F	G
40	(36.60) 1.440	(18.90) .744	(16.80) .661	(15.70) .618	(34.40) 1.354
50	(44.60) 1.756	(22.90) .902	(20.80) .819	(19.70) .776	(42.40) 1.669
60	(52.60) 2.071	(26.90) 1.059	(24.80) .976	(23.70) .933	(50.40) 1.984
80	(68.60) 2.701	(26.90) 1.059	(24.80) .976	(39.70) 1.563	(66.40) 2.614
100	(84.60) 3.331	(26.90) 1.059	(24.80) .976	(55.70) 2.193	(82.40) 3.244



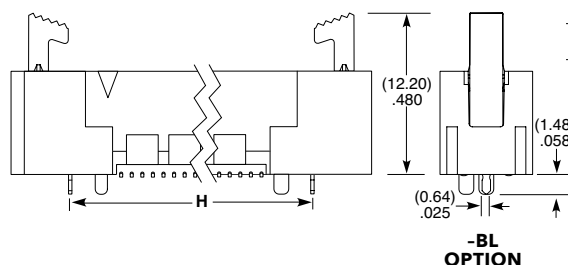
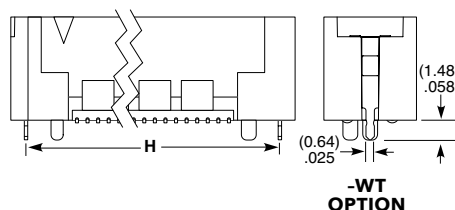
POSITIONS PER ROW	A	B
10	(9.40) .370	(7.20) .283
20	(17.40) .685	(15.20) .598
30	(25.40) 1.000	(23.20) .913



10, 20 & 30 POSITIONS



POSITIONS PER ROW	H
10	(14.90) .587
20	(22.90) .902
30	(30.90) 1.217
40	(42.10) 1.657
50	(50.10) 1.972
60	(58.10) 2.287
80	(74.10) 3.917
100	(90.10) 3.547



Note:
Some sizes, styles and
options are non-standard,
non-returnable.

View complete specifications at: samtec.com?HTEC8